

Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from, Europe, America and south Asia, supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts, Customers Priority, Honest Operation, and Considerate Service", our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip, ALPS, ROHM, Xilinx, Pulse, ON, Everlight and Freescale. Main products comprise IC, Modules, Potentiometer, IC Socket, Relay, Connector. Our parts cover such applications as commercial, industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



## Contact us

Tel: +86-755-8981 8866 Fax: +86-755-8427 6832

Email & Skype: info@chipsmall.com Web: www.chipsmall.com

Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China











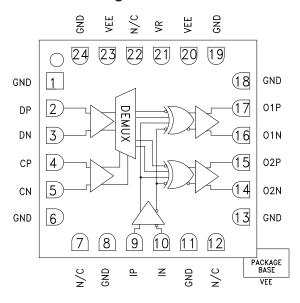
# 32 Gbps, 1:2 DEMUX WITH PROGRAMMABLE OUTPUT VOLTAGE

#### Typical Applications

The HMC955LC4B is ideal for:

- SONET OC-192
- Broadband Test & Measurement Equipment
- FPGA Interfacing Circuitry
- 16 G and 32 G Fiber Channel
- 100 Gbit Ethernet
- ADC Encoder

#### **Functional Diagram**



#### **Features**

Supports Data Rates up to 32 Gbps
660 mW Power Consumption
-3.3 V or +3.3 V Operation is Available
Supports Single-Ended and Differential Operation
24 Lead Ceramic 4x4 mm SMT Package: 16 mm<sup>2</sup>
Invert Port Allows Scrambling for SERDES
Application

#### **General Description**

The HMC955LC4B is a 1 to 2 Demux designed to support data transmission rates up to 32 Gbps. The demux uses both rising and falling edges of the half-rate clock to sample the data in sequence 01-02 and latches the data on the rising edge into the differential outputs. The demux also has high-speed clock synchronous invert input that allows for scrambling of the data. The HMC955LC4B also features an output level control pin, VR, which allows for loss compensation or for signal-level optimization.

All differential inputs to the HMC955LC4B are CML and terminated on-chip with 50 Ohms to the positive supply, GND, and may be AC or DC coupled. The differential CML outputs are source terminated to 50 Ohms and may also be AC or DC coupled. Outputs can be connected directly to a 50 Ohm ground-terminated system or drive devices with CML logic input. The HMC955LC4B operates from a single -3.3 V supply and is available in a ceramic ROHS-compliant 4x4 mm SMT package.

### Electrical Specifications, $T_A = +25$ °C, Vee = -3.3 V, VR = 0 V

	, ,				
Parameter	Conditions	Min.	Тур.	Max	Units
Power Supply Voltage (Vee)		-3.6	-3.3	-3.0	V
Power Supply Current			200		mA
Maximum Data Rate			32		Gbps
Maximum Clock Rate			16		GHz
Input Voltage Range, C and DIN		-1.5		0.5	V
Input Differential Range, C and DIN		0.1		2.0	Vp-p
Data Input Return Loss	Frequency <26 Gbps		10		dB
Clock Input Return Loss	Frequency <16 GHz		10		dB
Invert Input Return Loss	Frequency <16 GHz		10		dB

# **HMC955\* PRODUCT PAGE QUICK LINKS**

Last Content Update: 02/23/2017

## COMPARABLE PARTS 🖳

View a parametric search of comparable parts.

## **EVALUATION KITS**

· HMC955LC4B Evaluation Board

## **DOCUMENTATION**

#### **Data Sheet**

• HMC955 Data Sheet

## REFERENCE MATERIALS -

#### **Quality Documentation**

- Package/Assembly Qualification Test Report: LC4, LC4B (QTR: 2014-00380 REV: 01)
- Semiconductor Qualification Test Report: BiCMOS-C (QTR: 2013-00241)

## DESIGN RESOURCES 🖵

- HMC955 Material Declaration
- PCN-PDN Information
- · Quality And Reliability
- Symbols and Footprints

### **DISCUSSIONS**

View all HMC955 EngineerZone Discussions.

## SAMPLE AND BUY 🖵

Visit the product page to see pricing options.

## **TECHNICAL SUPPORT**

Submit a technical question or find your regional support number.

### DOCUMENT FEEDBACK 🖳

Submit feedback for this data sheet.





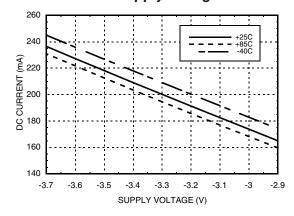
# 32 Gbps, 1:2 DEMUX WITH PROGRAMMABLE OUTPUT VOLTAGE

#### **Electrical Specifications** (continued)

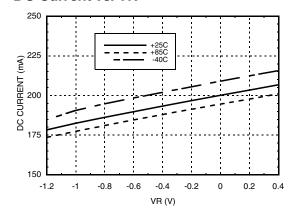
Parameter	Conditions	Min.	Тур.	Max	Units
	Single-Ended, peak-to-peak		500		mVp-p
Output Amplitude	Differential, peak-to-peak		1000		mVp-p
Output High Voltage			-25		mV
Output Low Voltage			-525		mV
Output Rise / Fall Time	Single-Ended, 20% - 80%		19		ps
Output Return Loss	Frequency <26 Gbps		10		dB
Random Jitter J <sub>R</sub>	rms <sup>[1]</sup>		<0.2		ps rms
VR Pin Current	VR = 0.0 V		3		mA
Deterministic Jitter, J <sub>D</sub>	δ - δ, 2 <sup>7</sup> -1 PRBS input <sup>[1]</sup>		<3		ps
Propagation Delay, tcpd	Rising Edge		119		ps
Data Setup Time, t <sub>s</sub>			1		ps
Data Hold Time, th			7		ps
Invert Setup Time, t <sub>is</sub>			0		ps
Invert Hold Time, tih			11		ps

<sup>[1]</sup> Jitter captured at 13 Gbps, 27-1 PRBS input.

#### DC Current vs. Supply Voltage [1][2]



#### DC Current vs. VR [2][3]



[1] VR = 0.0 V

[2] Frequency = 16 Gbps

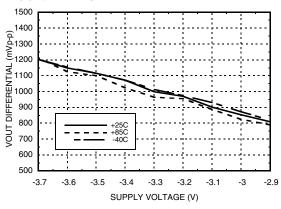
[3] Vee = -3.3 V



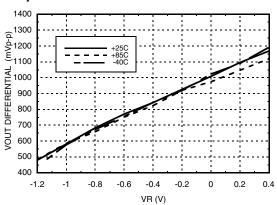


# 32 Gbps, 1:2 DEMUX WITH PROGRAMMABLE OUTPUT VOLTAGE

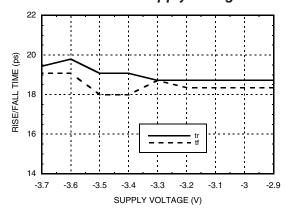
# Data Output Differential vs. Supply Voltage [1][2]



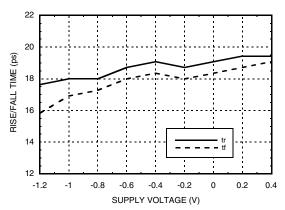
#### Output Differential vs. VR [2][4]



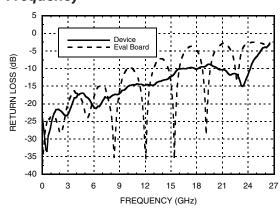
#### Rise / Fall Time vs. Supply Voltage [1][2]



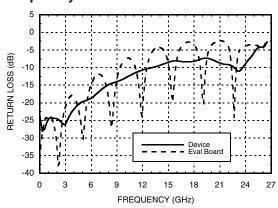
Rise / Fall Time vs. VR [2][4]



# Clock Input Return Loss vs. Frequency [1][3][4]



# Data Output Return Loss vs. Frequency [1][3][4]



[1] VR = 0.0V [4] Vee = -3.3 V [2] Frequency = 16 Gbps output [3] Device measured on evaluation board with gating after connector

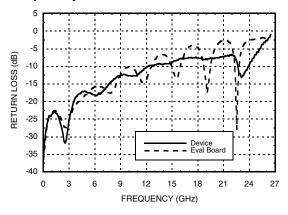
Information furnished by Analog Devices is believed to be accurate and reliable. However, no responsibility is assumed by Analog Devices for its use, nor for any infringements of patents or other rights of third parties that may result from its use. Specifications subject to change without notice. No license is granted by implication or otherwise under any patent or patent rights of Analog Devices. Trademarks and registered trademarks are the property of their respective owners.



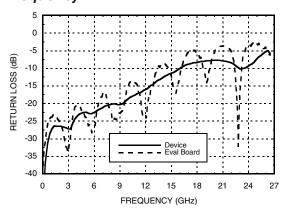


# 32 Gbps, 1:2 DEMUX WITH PROGRAMMABLE OUTPUT VOLTAGE

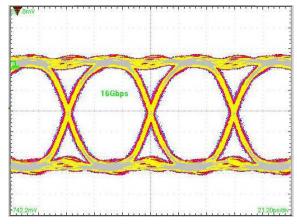
# Data Input Return Loss vs. Frequency [1][3][4]



# Invert Input Return Loss vs. Frequency [1][3][4]



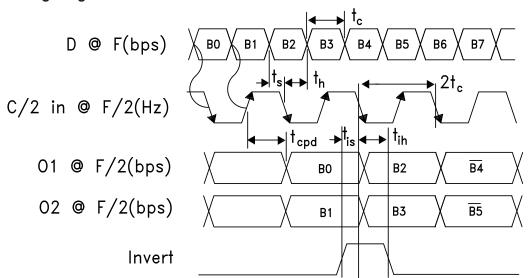
### Eye Diagram, 16 Gbps



#### [1] Test Conditions:

Single-ended 200 mV, 32 Gbps data input;16 GHz clock input Pattern generated with a 2<sup>7</sup>-1 quasi PN, 32 Gbps PRBS pattern Resulting in 16 Gbps, 2<sup>7</sup>-1 quasi PN output measured with Tektronix CSA 8000

#### **Timing Diagram**







# 32 Gbps, 1:2 DEMUX WITH PROGRAMMABLE OUTPUT VOLTAGE

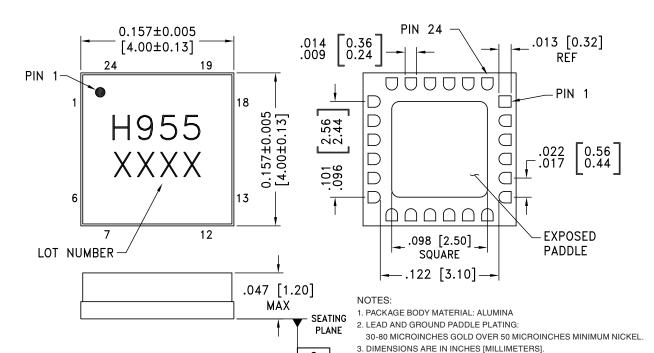
#### **Absolute Maximum Ratings**

Power Supply Voltage (Vee)	-3.75 V to +0.5 V	
Input Signals	-2 V to +0.5 V	
Output Signals	-1.5 V to +1 V	
Junction Temperature	125 °C	
Continuous Pdiss (T=85 °C) (derate 30 mW/°C above 85 °C	1.22 W	
Thermal Resistance (R <sub>th j-p</sub> ) Worse case junction to package paddle	32.8 °C/W	
Storage Temperature	-65 °C to +150 °C	
Operating Temperature	-40 °C to +85 °C	
ESD Sensitivity (HBM)	Class 1B	



### **Outline Drawing**

#### **BOTTOM VIEW**



### Package Information

Part Number	Package Body Material	Lead Finish	MSL Rating	Package Marking [2]
HMC955LC4B	Alumina, White	Gold over Nickel	MSL3 [1]	H955 XXXX

C-

- [1] Max peak reflow temperature of 260  $^{\circ}\text{C}$
- [2] 4-Digit lot number XXXX

4. LEAD SPACING TOLERANCE IS NON-CUMULATIVE.
5. PACKAGE WARP SHALL NOT EXCEED 0.05 mm DATUM -C6. ALL GROUND LEADS MUST BE SOLDERED TO PCB RF GROUND.

7. EXPOSED PADDLE MUST BE SOLDERED TO VEE





# 32 Gbps, 1:2 DEMUX WITH PROGRAMMABLE OUTPUT VOLTAGE

#### **Pin Descriptions**

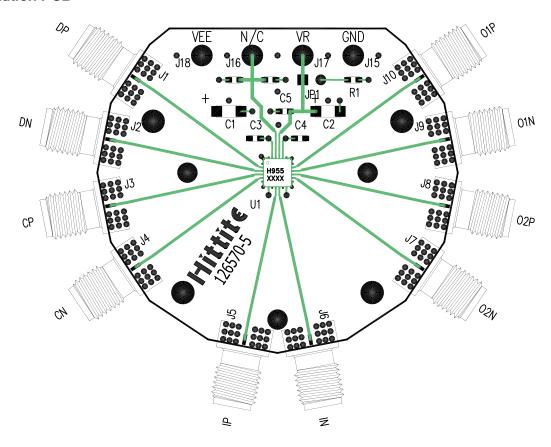
Pin Number	Function	Description	Interface Schematic
1, 6, 8, 11, 13, 18	GND	Signal Grounds	⊖ GND —
2, 3 4, 5 9, 10	DP, DN CP, CN IP, IN	Differential Data Inputs: Current Mode Logic (CML) referenced to positive supply.	GND GND SND
7, 12, 22	N/C	The pins are not connected internally; however, all data shown herein was measured with these pins connected to RF/DC ground externally.	
14, 15 16, 17	O2N, O2P O1N, O1P	Differential Outputs: Current Mode Logic (CML) referenced to positive supply	GND GND O GND OxPO OxN
19, 24	GND	Supply Grounds	⊖ GND =
20, 23 Package Base	Vee	These pins and the exposed paddle must be connected to the negative voltage supply.	
21	VR	Output level control. Output level may be increased or decreased by applying a voltage to VR per "Output Differential vs. VR" plot.	VR 0





# 32 Gbps, 1:2 DEMUX WITH PROGRAMMABLE OUTPUT VOLTAGE

#### **Evaluation PCB**



### List of Materials for Evaluation PCB EVAL01-HMC955LC4B [1]

Item	Description
J1 - J10	PCB Mount 2.92 mm RF Connectors
J15 - J18	DC Pin
JP1	0.1" Header with Shorting Jumper
C1, C2	4.7 μF Capacitor, Tantalum
C3 - C5	330 pF, Capacitor, 0603 Pkg
R1	10 Ohm Resistor, 0603 Pkg.
U1	HMC955LC4B High Speed Logic, 1:2 Demux
PCB [2]	126570 Evaluation Board

<sup>[1]</sup> Reference this number when ordering complete evaluation PCB

The circuit board used in the application should use RF circuit design techniques. Signal lines should have 50 Ohm impedance while the package ground leads should be connected directly to the ground plane similar to that shown. The exposed packaged base should be connected to Vee. A sufficient number of via holes should be used to connect the top and bottom ground planes. The evaluation circuit board shown is available from Hittite upon request. Install jumper on JP1 to short VR to GND for normal operation.

<sup>[2]</sup> Circuit Board Material: Arlon 25FR or Rogers 4350





# 32 Gbps, 1:2 DEMUX WITH PROGRAMMABLE OUTPUT VOLTAGE

#### **Application Circuit**

